



(0.635 mm) .025"



HIGH-SPEED COMBO RF & POWER

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?QMS

Insulator Material: Liquid Crystal Polymer Terminal & Ground Plane Material: Phosphor Bronze Plating: Au over 50 μ" (1.27 μm) Ni (Tin on Ground Plane Tail) Current Rating: Signal Contact: 2.6 A per pin (1 pin powered per row) Power Contact: 4.0 A per pin (4 pins powered per end) Ground Plane: 15.7 A per ground plane (1 ground plane powered)
Voltage Rating:
300 VAC mated with QFS
Operating Temp:
-55 °C to +125 °C

PROCESSING

Lead-Free Solderable:

RoHS Compliant:

Yes

SMT Lead Coplanarity: (0.10 mm) .004" max (026-078) Board Stacking:

For applications requiring more than two connectors per board, contact ipg@samtec.com

RECOGNITIONS

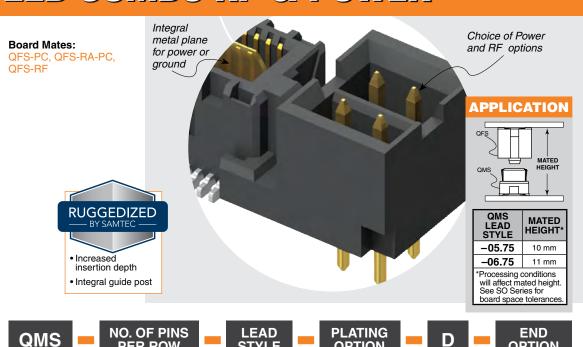
For complete scope of recognitions see www.samtec.com/quality



ALSO AVAILABLE (MOQ Required)

- Other platings
- Differential Pairs
- · Retention Pins
- 8 Power Pins/End for (1.60 mm) 0.62" thick board
- 4 or 8 Power Pins/End for (2.36 mm) .093" thick board
- 2 RF Connectors/End
- · Hot Pluggable Contact Samtec.

Note: Some lengths, styles and options are non-standard, non-returnable.





PER ROW

Specify LEAD **STYLE** from chart

Α

(5.38)

.212 (6.35)

STYLE

= 10 μ" (0.25 μm) Gold on Signal Pins and Ground Plane

(Tin on Signal Pin tails, and Ground Plane tails)

OPTION

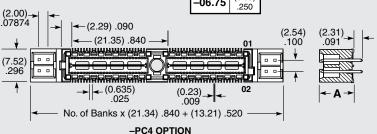
-PC4

OPTION

= 4 Power Pins per End for (1.60 mm) .062" thick Board (N/A with -RF1)

-RF1 = One RF

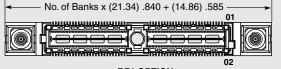
Plug per End (-05.75 only, not available with -PC4)



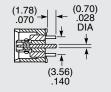
LEAD STYLE

-05.75

-06.75



-RF1 OPTION



OTHER SOLUTIONS



See SO Series for precision machined standoffs.